

RoHS

COMPLIANT

GREEN (5-2008)**

High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology



DESCRIPTION

VSMY2850 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- · Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR illumination

FEATURES

Package type: surface mount

• Package form: GW, RGW

• Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8

Peak wavelength: λ_p = 850 nm

· High reliability

· High radiant power

• Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 10^{\circ}$

Suitable for high pulse current operation

• Terminal configurations: gullwing or reverse gullwing

Package matches with detector VEMD2500X01 series

• Floor life: 4 weeks, MSL 2a, acc. J-STD-020

 Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC

• Halogen-free according to IEC 61249-2-21 definition

Note

** Please see document "Vishay Material Category Policy": www.vishay.com/doc?99902

PRODUCT SUMMARY				
COMPONENT	I _e (mW/sr)	φ (deg)	λ _P (nm)	t _r (ns)
VSMY2850RG	100	± 10	850	10
VSMY2850G	100	± 10	850	10

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY2850RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMY2850G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

Note

MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	Α
Power dissipation		P _V	190	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	- 40 to + 85	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	acc. figure 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W

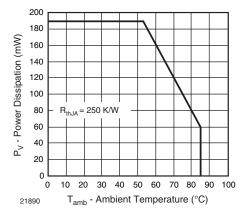


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

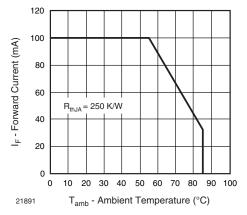


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Farmer described	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F		1.65	1.9	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \ \mu\text{s}$	V _F		2.9		V
Tanana Maria da Maria	I _F = 1 mA	TK _{VF}		- 1.45		mV/K
Temperature coefficient of V _F	I _F = 10 mA	TK _{VF}		- 1.3		mV/K
Reverse current		I _R	not desigr	ned for reverse	operation	μΑ
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ		125		pF
Design of Colors 2	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	50	100	150	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e		850		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe		55		mW
Temperature coefficient of radiant power	I _F = 100 mA	TΚφ _e		- 0.35		%/K
Angle of half intensity		φ		± 10		deg
Peak wavelength	I _F = 100 mA	λρ	840	850	870	nm
Spectral bandwidth	I _F = 30 mA	Δλ		30		nm
Temperature coefficient of λ_p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		10		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		10		ns
Virtual source diameter		d		1.5		mm

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

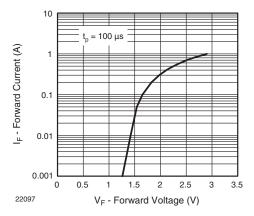


Fig. 3 - Forward Current vs. Forward Voltage

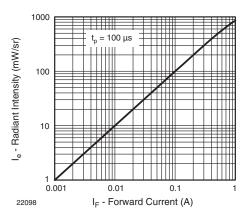


Fig. 4 - Radiant Intensity vs. Forward Current

SOLDER PROFILE

300 max. 260 250 245 -240 °C 217 °C 200 Femperature (°C) max. 30 s 150 max. 120 s max. 100 s 100 50 max. ramp up 3 °C/s max. ramp down 6 °C/s 250 100 150 Time (s)

Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

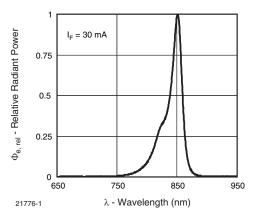


Fig. 5 - Relative Radiant Power vs. Wavelength

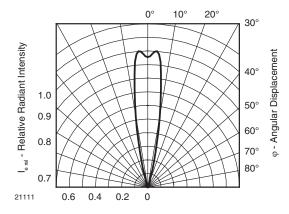


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

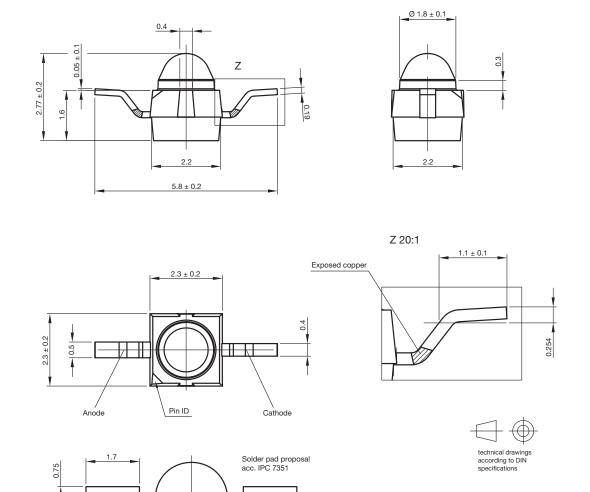
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMY2850RG



Ø 2.3 ± 0.1

6.7

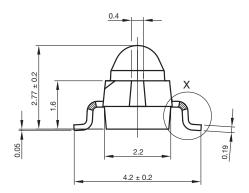
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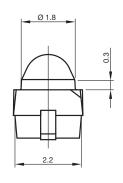
Issue: 1; 18.03.10

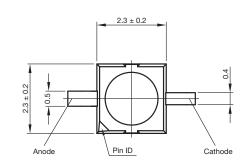
22100

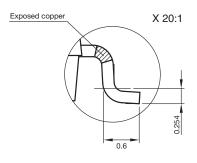
Not indicated tolerances \pm 0.1

PACKAGE DIMENSIONS in millimeters: VSMY2850G

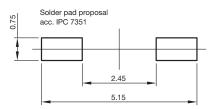




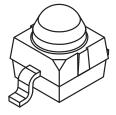








Not indicated tolerances \pm 0.1

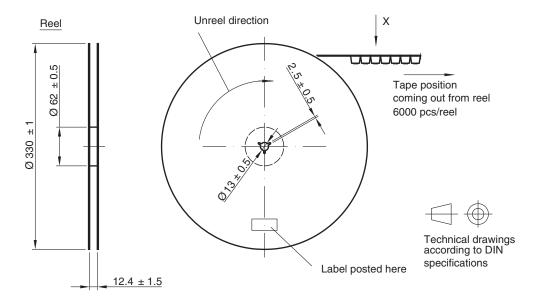


Drawing-No.: 6.544-5383.03-4 Issue: 1; 18.03.10

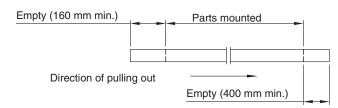
22099



TAPING AND REEL DIMENSIONS in millimeters: VSMY2850RG

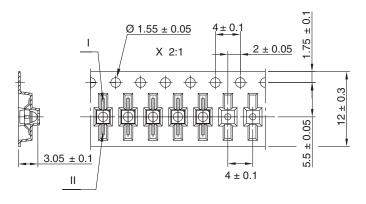


Leader and trailer tape:



Terminal position in tape

Devicce	Lead I	Lead II
VEMT2000		
VEMT2500	Collector	Emitter
VEMD2000		
VEMD2500	0-4	A I -
VSMB2000	Cathode	Anode
VSMG2000		
VSMY2850RG	Anode	Cathode

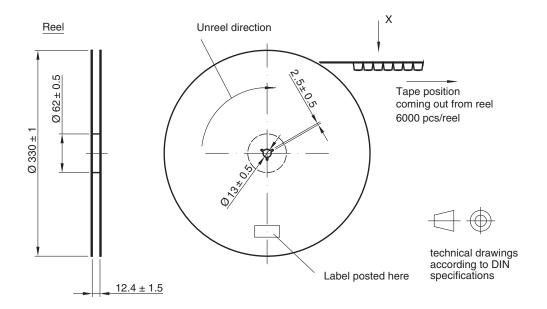


Drawing-No.: 9.800-5100.01-4

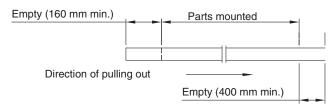
Issue: 2; 18.03.10

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TAPING AND REEL DIMENSIONS in millimeters: VSMY2850G

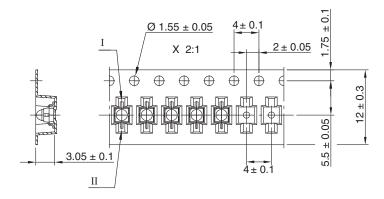


Leader and trailer tape:



Terminal position in tape

Devicce	Lead I	Lead II
VEMT2020		
VEMT2520	Collector	Emitter
VSMB2020		
VSMG2020	0-4	Al -
VEMD2020	Cathode	Anode
VEMD2520		
VSMY2850G	Anode	Cathode



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

21571





Vishay

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